

Manufacturing of multilayer ceramic capacitors by laser machining

CNES-Exxelia contract n° 180649/00

October 10, 2018

Why laser machining ?

- Exxelia's core target has always been and is still high reliability passive components conception, development and supply, both standard and custom-design models
- For MLCC's, it means (among others) development of various designs, to fit customer requirements
- Classical MLCC's manufacturing technologies allow to build only parallelepipedic or circular capacitors
- The aim here is to test a method to be able to build various shapes, needed in particular (but not only) for filtering (feed-through) applications
- Study is in progress (with help of CNES), to build and test filtering MLCC's, mono or multi capacitances, with miniaturized circular shapes or custom-design shapes

⇒ **laser machining**

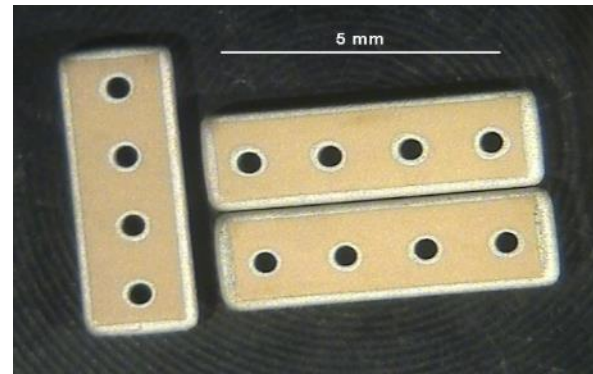
Examples of previous developments, mechanical machining



Single capacitance miniaturized model



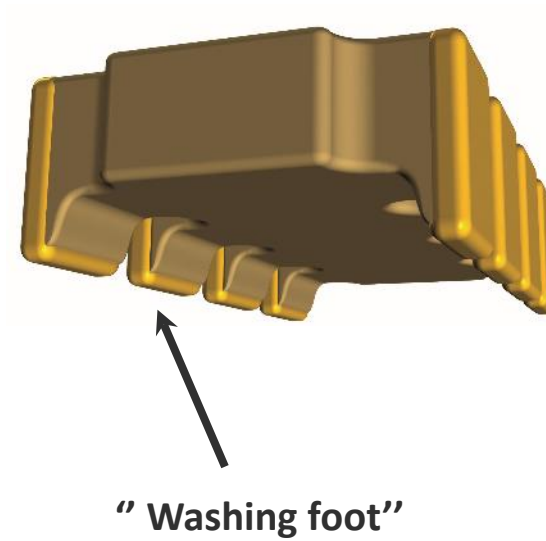
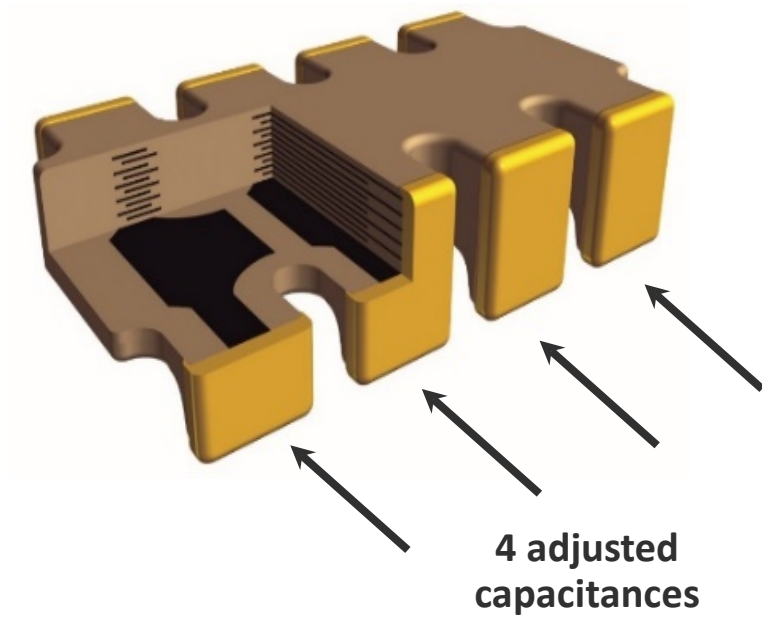
Multi capacitance miniaturized model



Multicapacitance custom-design miniaturized model

Examples of previous developments, laser machining

Multicapacitance custom-design miniaturized model



1206 size

Laser machining benefit pour MLCC's custom design manufacturing

Why UV laser ?

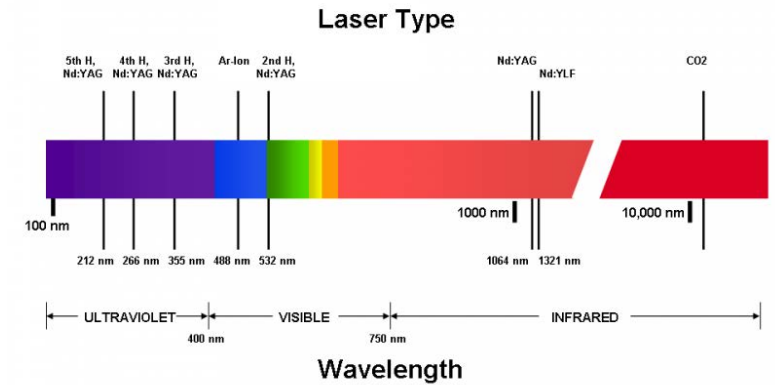
Photons emitted in the UV spectra have an energy much higher than those emitted in IR.

Absorbed photons give a kinetic energy that brake links of matter's molecules ; particles are ejected with a very high speed = **photochemical ablation**.

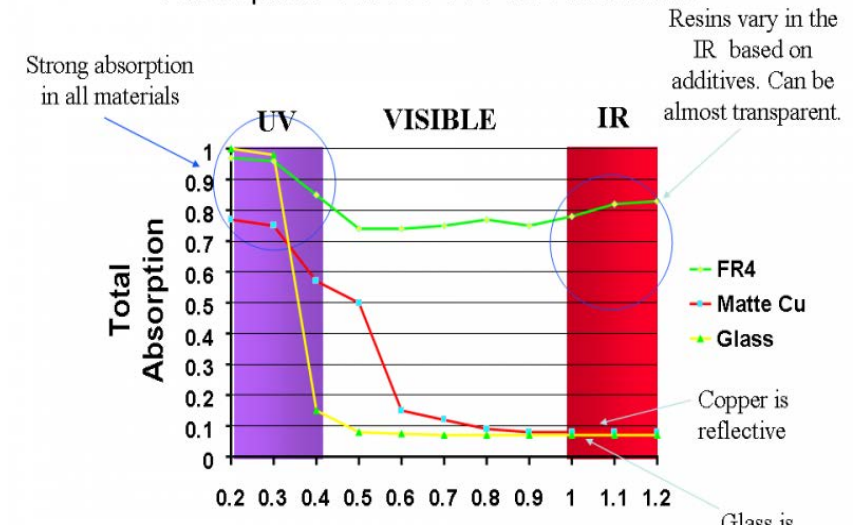
LASER energy emitted in UV spectra is absorbed by metallic materials (copper, steel, aluminium...) as well as by insulating materials (polymers, ceramics, industrial diamond...)

M.U.L. use LASER sources with UV (355nm) emission to carry out custom-design micromachining

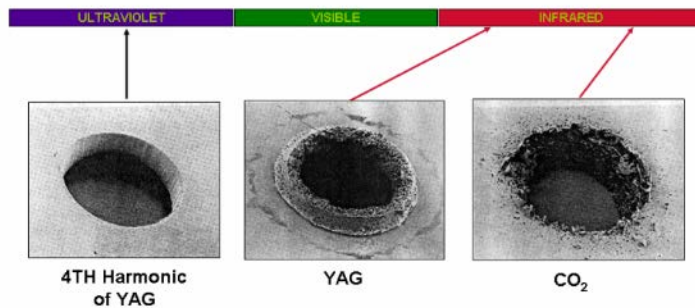
Laser Wavelengths For Production



Absorption Curves of PWB Materials

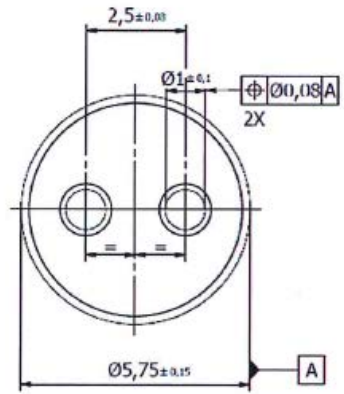


Ablation Versus Vaporization

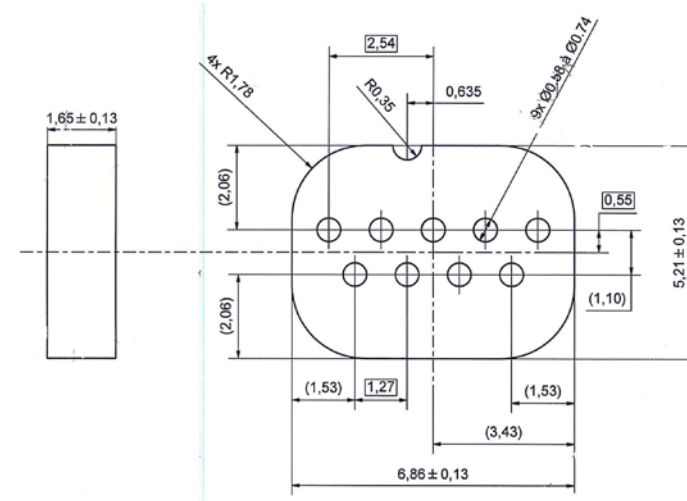


Drilling of the same material using lasers of different wavelength

Test vehicles for evaluation of laser machining

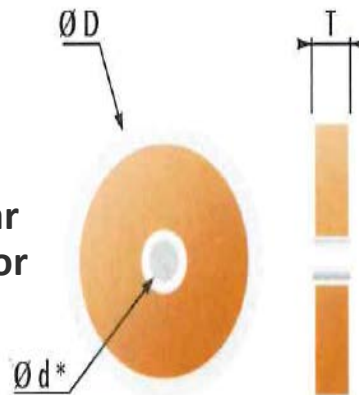


Double capacitance circular feedthrough capacitor



Multi capacitance custom design shape feedthrough capacitor

Single capacitance circular feedthrough mini capacitor



$D = 1,4\text{mm} (-0,1/0)$

$d = 0,5\text{mm} (0/+0,05)$

$T = 1\text{ mm max}$

Green ceramics laser machining : first trials on standard "TBC"



Laminated green block after laser machining, MLCC's still in place



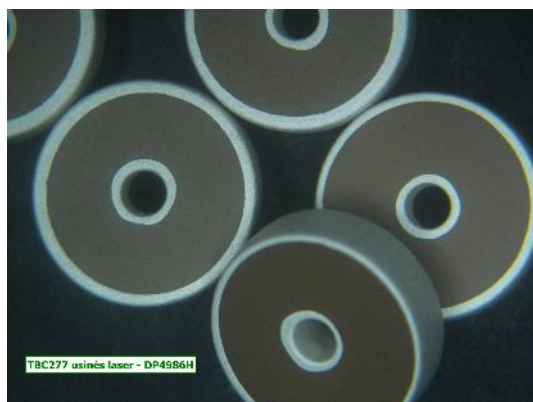
Laminated green block after laser machining, MLCC's removed



Green MLCC's after laser machining



Laser machined circular MLCC's, fired, grinded



Laser machined circular MLCC's, terminated



Laser machined circular MLCC's, gold plated

⇒ Feasibility validated

Multi capacitance custom design shape MLCC's development



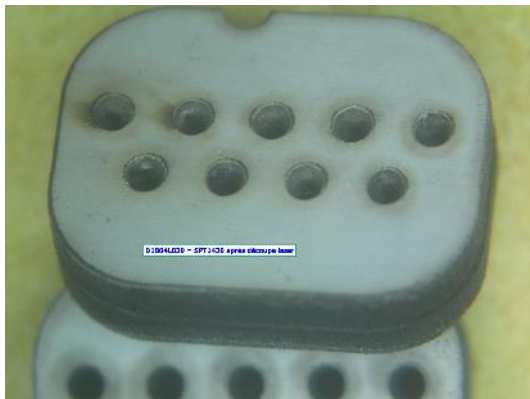
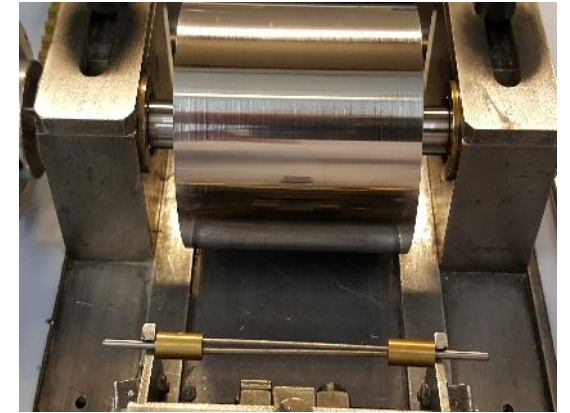
Green MLCC's after laser machining



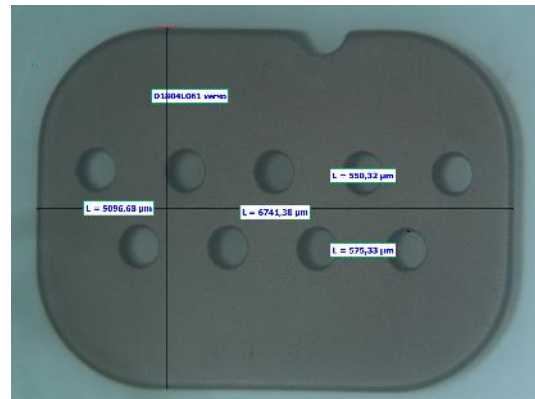
Laser machined circular MLCC's, fired, grinded



Special tool for termination deposit on roll equipment



Green MLCC's after laser machining



Laser machined custom design shape MLCC's, fired, grinded



New technology for termination deposit

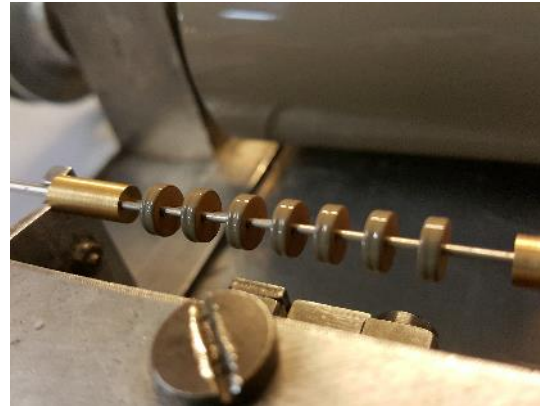


Syringe on 4 axes robot deposit

Multi capacitance custom design shape MLCC's development



Green MLCC's after laser machining



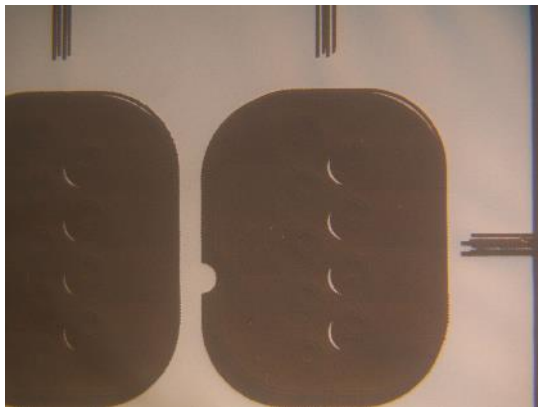
Terminated MLCC's



Gold plated parts,
2 x 50nF (0/ +100%) 200V



Delivered to customer



Overlay test of printing screens
⇒ to be improved



DPA : bad overlay ⇒ electrode shifting ⇒ shorts

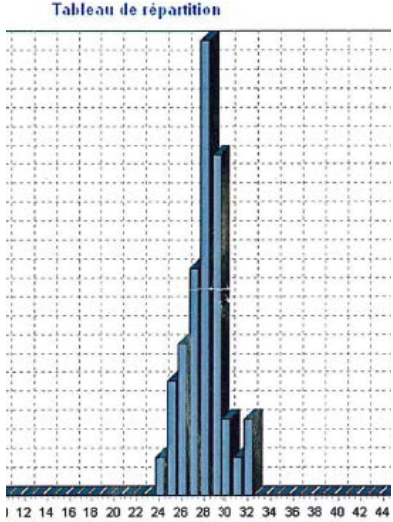


Trials to be done on another manufacturing line, using optical centering



Test in progress

Laser machining benefit for MLCC's custom design manufacturing



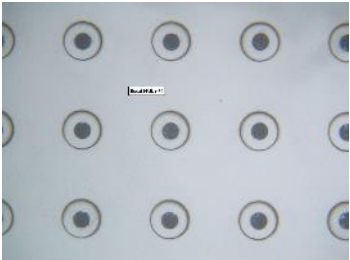
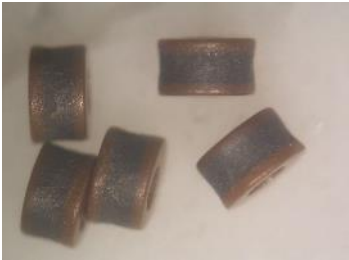
Close capacitance distribution
(type 2 ceramic, 50nF each capacitance)



**Trials to be done on
parallelepipedic parts
(vs blade cutting) to
validate or invalidate
this improvement**



Micro-feedthrough MLCC's - Punching



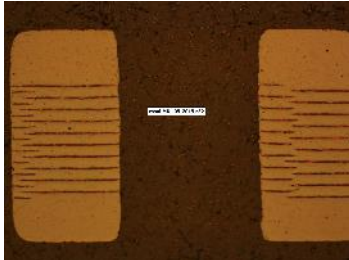
Micro-feedthrough MLCC's - Laser machining



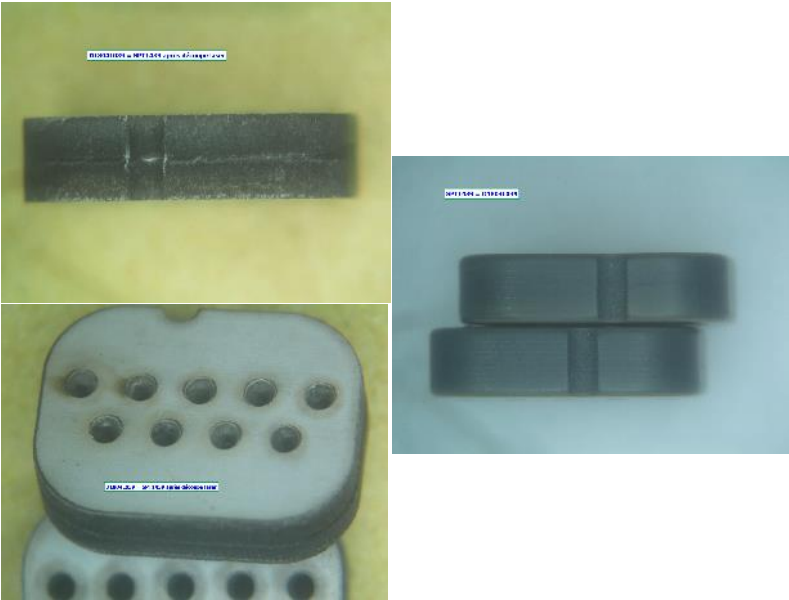
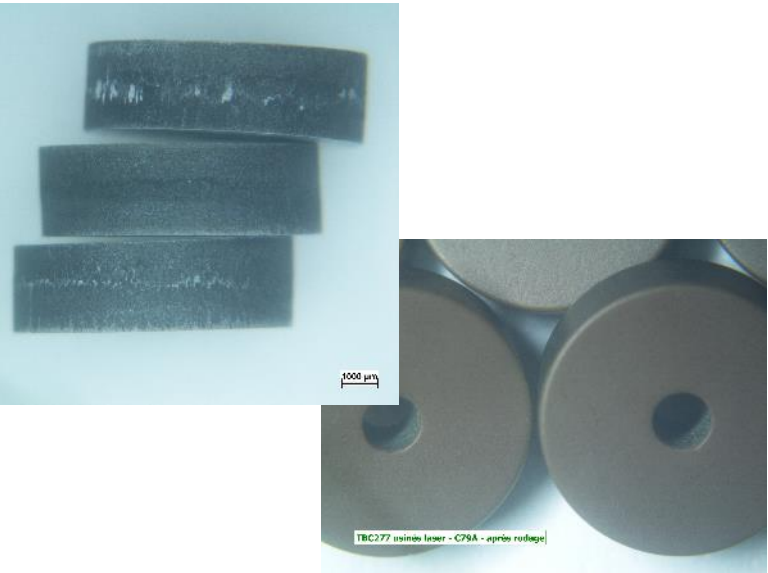
$\Phi_{ext}=1,3-1,4mm$
 $\phi_{int}=0,5-0,55mm$
 $e = 1mm \text{ max}$



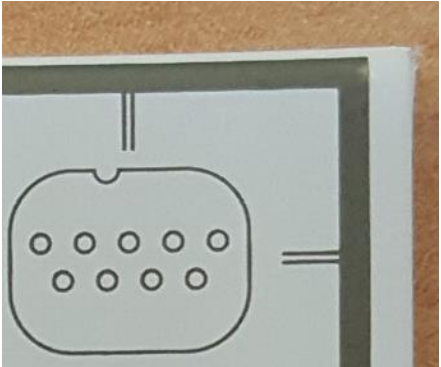
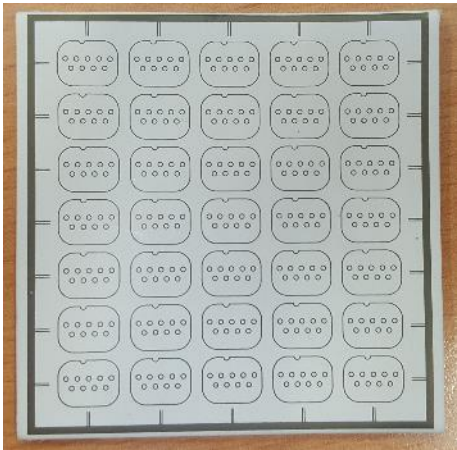
**More accurate
Better geometric
definition**



What do we have to improve ?



Up to 1mm thick, single-side machining
Thicker than 1mm, double-side machining needed
⇒ ⚠ matching after rollover



Machining marker needed
⇒ one more printing screen



Thanks a lot for
your attention



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Maybe you have
some questions ?



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